

#### PCN# : P5A9AAB Issue Date : Jul. 20, 2016

#### **DESIGN/PROCESS CHANGE NOTIFICATION**

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples.

#### Implementation of change:

Expected First Shipment Date for Changed Product :Oct. 18, 2016

Expected First Date Code of Changed Product :1643

Description of Change (From) :

1) Wire bonding with 1.0mils PCC and 1.3mils Au.

2) Assembly in Fairchild Semiconductor Cebu and sub-contractor Philippines

|                  |               |  | BOM                           |               |                                       |                          |                    |  |  |  |  |
|------------------|---------------|--|-------------------------------|---------------|---------------------------------------|--------------------------|--------------------|--|--|--|--|
| Package          | Assembly Site | Leadframe  | Die & Clip Attach<br>Material | Clip Material | Wire                                  | Mold Compound            | Terminal<br>Finish |  |  |  |  |
| DRMOS<br>PQFN6x6 |               | C194 Cu leadframe<br>with Ag spot plating        | Indium Corp. NC-<br>SMQ75     | C194 Cu Clip  | 1.0 mils PCC wire<br>1.3 mils Au wire | Hitachi<br>CEL9240HF10LS | Sn                 |  |  |  |  |
| DRMOS<br>PQFN6x6 |               | C194 Cu <u>leadframe</u><br>with Ag spot plating | Indium Corp. NC-<br>SMQ75     | C194 Cu Clip  | 1.0 mils PCC wire                     | Hitachi<br>CEL9220HF10   | Sn                 |  |  |  |  |

Description of Change (To) :

1) Standardize wire bonding to 1.0mils PCC only.

2) Added alternate assembly location in sub-contractor Philippines and Malaysia. No changes to current marketing outline specification.

|                  |               | ВОМ  |                           |               |                      |                          |                    |  |  |  |
|------------------|---------------|--|---------------------------|---------------|----------------------|--------------------------|--------------------|--|--|--|
| Package          | Assembly Site | Leadframe  | Die Attach<br>Material    | Clip Material | Wire                 | Mold Compound            | Terminal<br>Finish |  |  |  |
| DRMOS<br>PQFN6x6 |               | C194 Cu leadframe<br>with Ag spot plating        | Indium Corp. NC-<br>SMQ75 | C194 Cu Clip  | 1.0 mils PCC<br>wire | Hitachi<br>CEL9240HF10LS | Sn                 |  |  |  |
| DRMOS<br>PQFN6x6 |               | C194 Cu <u>leadframe</u><br>with Ag spot plating | Indium Corp. NC-<br>SMQ75 | C194 Cu Clip  | 1.0 mils PCC<br>wire | Hitachi<br>CEL9240HF10LS | Sn                 |  |  |  |
| DRMOS<br>PQFN6x6 |               | C194 Cu <u>leadframe</u><br>with Ag spot plating | Indium Corp. NC-<br>SMQ75 | C194 Cu Clip  | 1.0 mils PCC<br>wire | Hitachi<br>CEL9220HF10   | Sn                 |  |  |  |

Reason for Change:

•Improved supply flexibility.

•Better quality and yields through equipment and facility upgrades. •Increased automation in handling and inspection in assembly.

Fairchild partnerships with foundries and assembly subcontractors.Best manufacturing practices- access to many customer methods and practices.

•Advanced technology for fast ramp of future new products and technologies.



### Affected Product(s):

| FDMF6705B         | FDMF6705V         | FDMF6706B         |
|-------------------|-------------------|-------------------|
| FDMF6706C         | FDMF6707B         | FDMF6707B_SN00244 |
| FDMF6707C         | FDMF6707V         | FDMF6820A         |
| FDMF6820A_F065    | FDMF6820B         | FDMF6820B_F065    |
| FDMF6820C         | FDMF6820C_SN00295 | FDMF6821A         |
| FDMF6821B         | FDMF6821C         | FDMF6823A         |
| FDMF6823A_F065    | FDMF6823B         | FDMF6823C         |
| FDMF6823C_SN00248 | FDMF6824A         | FDMF6824B         |
| FDMF6824B_SN00323 | FDMF6824C         | FDMF6833C         |
| FDMF6840C         | ZSPM9000AI1R      | ZSPM9010ZA1R      |
| ZSPM9060ZA1R      |                   |                   |

## QUALIFICATION DATA REPORT P5A9AAB - DrMOS PCN

| Qualification Plan                                      | Device                       | Package                 | Package & Asse             | embly Locatio   | n No. d        | of Lots        |         |
|---|------------------------------|-------------------------|----------------------------|---|----------------|----------------|---------|
| Q20140167   | FDMF6820B                    | PQBFN                   | AMK                        | KOR   | 3              |                |         |
| Test Descriptior  | n Cor                        | ndition                 | Standard                   | Duration  | Sample<br>size | No. of<br>lots | Results |
| Preconditioning, MS                                     | L 1 Peak Te<br>(260°C)       | mp                      | JESD22-A113                |   | 45, 77         | 15             | 0/1059  |
| Highly Accelerated<br>Stress Test                       | Precond<br>85%RH,<br>Bias    |                         | JESD22-A110                | 96 hrs  | 45             | 3              | 0/135   |
| High Temperature<br>Operating Life                      | Precond<br>125C, Bi          | •                       | JESD22-A108                | 1000 hrs  | 77             | 3              | 0/231   |
| Unbiased Highly<br>Accelerated Stress                   | Precond<br>Test 85%RH,       | -                       | JESD22-A118                | 96 hrs<br>192 hrs   | 77             | 3              | 0/231   |
| Temperature Cycle                                       | Precond<br>-65C, 15          |                         | JESD22-A104                | 50 cycles<br>250<br>cycles<br>500<br>cycles<br>1000<br>cycles | 77             | 3              | 0/231   |
| High Temperature<br>Storage Life                        | Precond<br>150C              | itioning,               | JESD22- A103               | 168 hrs<br>500 hrs<br>1000 hrs                                | 77             | 3              | 0/231   |
| Power Cycle   | Precond<br>Delta100<br>cycle | itioning,<br>)CC, 2 min | MILSTD-750-<br>1036        | 5000<br>cycles<br>10000<br>cycles                             | 77             | 4              | 0/308   |
| Destructive Physical<br>Analysis<br>(after 500cyc TMCL) | NA                           |                         | AEC-Q101-<br>004 Section 4 | After<br>TMCL   | 3              | 3              | 0/9     |

| Qualification Plan | Device    | Package | Package & Assembly Location | No. of Lots |
|--------------------|-----------|---------|-----------------------------|-------------|
| Q20140340          | FDMF6820B | PQBFN   | AMKOR                       | 3           |

| Test Description                  | Condition                                | Standard        | Duration   | Sample<br>size | No. of<br>lots | Results |
|-----------------------------------|--|-----------------|------------|----------------|----------------|---------|
| Preconditioning, MSL 1            | Peak Temp (260°C)                        | JESD22-<br>A113 |            | 45, 77         | 15             | 0/366   |
| Highly Accelerated Stress<br>Test | Preconditioning,<br>85%RH, 110C,<br>Bias | JESD22-<br>A110 | 300 hrs    | 45             | 3              | 0/135   |
| Temperature Cycle                 | Preconditioning,<br>-65C, 150C           | JESD22-<br>A104 | 100 cycles | 77             | 3              | 0/231   |

| Qualification Plan | Device    | Package | Package & Assembly Location | No. of Lots |
|--------------------|-----------|---------|-----------------------------|-------------|
| Q20140306          | FDMF6840C | PQBFN   | AMKOR                       | 3           |

| Test Description                                     | Condition                                | Standard                   | Duratio<br>n                                     | Sample<br>size | No. of<br>lots | Results |
|--|--|----------------------------|--|----------------|----------------|---------|
| Preconditioning, MSL 1                               | Peak Temp (260°C)                        | JESD22-<br>A113            |  | 45, 77         | 12             | 0/828   |
| Highly Accelerated Stress<br>Test                    | Preconditioning,<br>85%RH, 110C,<br>Bias | JESD22-<br>A110            | 132 hrs<br>300 hrs                               | 77             | 3              | 0/231   |
| Unbiased Highly<br>Accelerated Stress Test           | Preconditioning,<br>85%RH, 130C          | JESD22-<br>A118            | 96 hrs<br>192 hrs                                | 77             | 3              | 0/231   |
| Temperature Cycle                                    | Preconditioning,<br>-65C, 150C           | JESD22-<br>A104            | 100<br>cycles<br>500<br>cycles<br>1000<br>cycles | 77             | 3              | 0/231   |
| High Temperature Storage<br>Life                     | Preconditioning,<br>150C                 | JESD22-<br>A103            | 168 hrs<br>500 hrs<br>1000 hrs                   | 77             | 3              | 0/231   |
| Destructive Physical Analysis<br>(after 500cyc TMCL) | NA                                       | AEC-Q101-<br>004 Section 4 | After<br>TMCL                                    | 2              | 3              | 0/6     |

| Qualification Plan | Device    | Package | Package & Assembly Location | No. of Lots |
|--------------------|-----------|---------|-----------------------------|-------------|
| Q20150476A         | FDMF6820B | PQBFN   | ASE-M                       | 3           |

| Test Description   | Condition                             | Standard                  | Duration   | Sample<br>size | No.<br>of<br>lots | Results |
|--|---------------------------------------|---------------------------|--|----------------|-------------------|---------|
| Preconditioning, MSL 1                                   | Peak Temp (260°C)                     | JESD22-A113               |  | 45, 77         | 15                | 0/828   |
| Highly Accelerated Stress<br>Test                        | Preconditioning,<br>85%RH, 130C, Bias | JESD22-A110               | 96 hrs   | 45             | 3                 | 0/135   |
| Unbiased Highly<br>Accelerated Stress Test               | Preconditioning,<br>85%RH, 130C       | JESD22-A118               | 96 hrs<br>192 hrs                                | 77             | 3                 | 0/231   |
| Temperature Cycle  | Preconditioning,<br>-65C, 150C        | JESD22-A104               | 100<br>cycles<br>500<br>cycles<br>1000<br>cycles | 77             | 3                 | 0/231   |
| High Temperature Storage<br>Life                         | Preconditioning,<br>150C              | JESD22- A103              | 168 hrs<br>500 hrs<br>1000 hrs                   | 77             | 3                 | 0/231   |
| Destructive Physical<br>Analysis<br>(after 1000cyc TMCL) | NA                                    | AEC-Q101-004<br>Section 4 | After<br>TMCL                                    | 3              | 3                 | 0/9     |

| Qualification Plan | Device    | Package | Package & Assembly Location | No. of Lots |
|--------------------|-----------|---------|-----------------------------|-------------|
| Q20150495          | FDMF6840C | PQBFN   | ASE-M                       | 3           |

| Test Description                  | Condition                             | Standard        | Duration   | Sample<br>size | No. of<br>lots | Results |
|-----------------------------------|---------------------------------------|-----------------|------------|----------------|----------------|---------|
| Preconditioning, MSL 1            | Peak Temp (260°C)                     | JESD22-<br>A113 |            | 45, 77         | 6              | 0/366   |
| Highly Accelerated<br>Stress Test | Preconditioning,<br>85%RH, 110C, Bias | JESD22-<br>A110 | 300 hrs    | 45             | 3              | 0/135   |
| Temperature Cycle                 | Preconditioning,<br>-65C, 150C        | JESD22-<br>A104 | 100 cycles | 77             | 3              | 0/231   |

| Qualification Plan | Device    | Package | Package & Assembly Location | No. of Lots |
|--------------------|-----------|---------|-----------------------------|-------------|
| Q20160052A         | FDMF6821B | PQBFN   | Cebu                        | 3           |

| Test Description  | Condition                                | Standard                      | Duration                                   | Sample<br>size | No. of<br>lots | Results |
|---|--|-------------------------------|--|----------------|----------------|---------|
| Preconditioning, MSL 1                                  | Peak Temp<br>(260°C)                     | JESD22-<br>A113               |  | 77             | 3              | 0/231   |
| Highly Accelerated Stress<br>Test                       | Preconditioning,<br>85%RH, 130C,<br>Bias | JESD22-<br>A110               | 96hrs<br>192 hrs                           | 77             | 1              | 0/77    |
| Temperature Cycle                                       | Preconditioning,<br>-65C, 150C           | JESD22-<br>A104               | 100 cycles<br>500 cycles<br>1000<br>cycles | 77             | 1              | 0/77    |
| High Temperature<br>Storage Life                        | Preconditioning,<br>150C                 | JESD22-<br>A103               | 168 hrs<br>500 hrs<br>1000 hrs             | 77             | 1              | 0/77    |
| Destructive Physical<br>Analysis<br>(after 500cyc TMCL) | NA                                       | AEC-Q101-<br>004<br>Section 4 | After<br>TMCL                              | 2              | 1              | 0/2     |



## Title : Qualification Report for PCN : P5A9AAB

Date : Jul. 20, 2016

### Affected devices :

С

| Product   | Customer Part NumberBBB | Drawing |
|-----------|-------------------------|---------|
| FDMF6705B | Y                       | Ν       |
| FDMF6820A | Y                       | Ν       |
| FDMF6823A | Y                       | Ν       |
| FDMF6823B | Y                       | Ν       |
| FDMF6823C | Y                       | N       |
| FDMF6824B | Y                       | Ν       |

С

| Product   | Customer Part NumberBBB | Drawing |
|-----------|-------------------------|---------|
| FDMF6706B | Y                       | Ν       |
| FDMF6707C | Y                       | Ν       |
| FDMF6824A | Y                       | N       |
| FDMF6824C | Y                       | N       |
| FDMF6840C | Y                       | Ν       |

**Qualification Test Summary :** 

| Qualification Plan | Device    | Paokage | Package & Assembly Location | No. of Lots |
|--------------------|-----------|---------|-----------------------------|-------------|
| Q20140167          | FDMF6820B | POBEN   | AMKOR                       | 8           |

| Test Description  | Condition                                      | 8tandard                   | Duration  | 8ample<br>size | No. of<br>lots | Results |
|---|--|----------------------------|---|----------------|----------------|---------|
| Preconditioning, MSL 1                                  | Peak Temp<br>(260°C)                           | JE8D22-A113                |   | 45, 77         | 15             | 0/1059  |
| Highly Accelerated<br>Stress Test                       | Preconditioning,<br>85%RH, 130C,<br>Blas       | JE8022-A110                | 96 hrs  | 45             | 8              | 0/135   |
| High Temperature<br>Operating Life                      | Preconditioning,<br>125C, Blas                 | JE8022-A108                | 1000 hrs  | 77             | ø              | 0/231   |
| Unblased Highly<br>Accelerated Stress Test              | Preconditioning,<br>85%RH, 130C                | JE8022-A118                | 96 hrs<br>192 hrs   | 77             | ø              | 0/231   |
| Temperature Cycle                                       | Preconditioning,<br>-65C, 150C                 | JE8D22-A104                | 50 cycles<br>250<br>cycles<br>500<br>cycles<br>1000<br>cycles | 77             | 3              | 0/231   |
| High Temperature<br>Storage Life                        | Preconditioning,<br>150C                       | JE8022-A108                | 168 hrs<br>500 hrs<br>1000 hrs                                | 77             | 8              | 0/231   |
| Power Cycle   | Preconditioning,<br>Delta100CC, 2 min<br>cycle | MIL8TD-750-<br>1036        | 5000<br>cycles<br>10000<br>cycles                             | 77             | 4              | 0/308   |
| Destructive Physical<br>Analysis<br>(after 500cyc TMCL) | NA   | AEC-Q101-<br>004 Section 4 | After<br>TMCL   | 3              | 3              | 0/9     |

# Qualification Plan Device Package Package & Accembly Location No. of Lots Q20140340 FDMF6820B PQBFN AMKOR 3

| 1 |                                  |  |                 |            |                |                |         |
|---|----------------------------------|--|-----------------|------------|----------------|----------------|---------|
|   | Test Description                 | Condition                                | 8tandard        | Duration   | 8ample<br>cize | No. of<br>lots | Results |
|   | Preconditioning, MSL 1           | Peak Temp (260°C)                        | JE8022-<br>A113 |            | 45, 77         | 15             | 0/366   |
|   | Highly Accelerated Stess<br>Test | Preconditioning,<br>85%RH, 110C,<br>Blas | JE8D22-<br>A110 | 300 hrs    | 45             | 8              | 0/135   |
|   | Temperature Cycle                | Preconditioning,<br>-65C, 150C           | JE8022-<br>A104 | 100 cycles | 77             | s              | 0/231   |

## Qualification Plan Device Package Package & Accembly Location No. of Lots Q20140306 FDMF6840C PQBFN AMKOR 3

| Test Description                                     | Condition                                | Standard                   | Duratio<br>n                                     | 8ample<br>cize | No. of<br>lots | Results |
|--|--|----------------------------|--|----------------|----------------|---------|
| Preconditioning, MSL 1                               | Peak Temp (260°C)                        | JE8022-<br>A113            |  | 45, 77         | 12             | 0/828   |
| Highly Accelerated Stess<br>Test                     | Preconditioning,<br>85%RH, 110C,<br>Blas | JE8022-<br>A110            | 132 hrs<br>300 hrs                               | 77             | 3              | 0/231   |
| Unbiased Highly<br>Accelerated Stress Test           | Preconditioning,<br>85%RH, 130C          | JE8022-<br>A118            | 96 hrs<br>192 hrs                                | 77             | 3              | 0/231   |
| Temperature Cycle                                    | Preconditioning,<br>-65C, 150C           | JE8D22-<br>A104            | 100<br>cycles<br>500<br>cycles<br>1000<br>cycles | 77             | 3              | 0/231   |
| High Temperature Storage<br>Life                     | Preconditioning,<br>150C                 | JE8022-<br>A103            | 168 hrs<br>500 hrs<br>1000 hrs                   | 77             | з              | 0/231   |
| Destructive Physical Analysis<br>(after 500cyc TMCL) | NA                                       | AEC-Q101-<br>004 Section 4 | After<br>TMCL                                    | 2              | з              | 0/6     |

## Qualification Plan Device Package Package & Assembly Location No. of Lots Q20150476A FDMF8820B PQBFN A8E-M 3

| Test Description   | Condition                              | Standard                   | Duration   | 8ample<br>size | No.<br>of<br>lots | Results |
|--|--|----------------------------|--|----------------|-------------------|---------|
| Preconditioning, MSL 1                                   | Peak Temp (250°C)                      | JES022-A113                |  | 45, 17         | 15                | 0/525   |
| Highly Accelerated Stress<br>Test                        | Preconditioning,<br>8516RH, 130C, Blas | JES022-A110                | 95 hrs   | 45             | 3                 | 0/125   |
| Unbiased Highly<br>Accelerated Stress Test               | Preconditioning,<br>85%RH, 130C        | JES022-A118                | 95 hrs<br>192 hrs                                | π              | 3                 | 0/231   |
| Temperature Cycle  | Preconditioning,<br>-85C, 150C         | JES022-A104                | 100<br>cycles<br>500<br>cycles<br>1000<br>cycles | π              | 3                 | 0/231   |
| High Temperature Storage<br>Life                         | Preconditioning,<br>150C               | JES022- A103               | 165 hrs<br>500 hrs<br>1000 hrs                   | π              | 3                 | 0/221   |
| Destructive Physical<br>Analysis<br>(after 1000cyc TMCL) | NA                                     | AEC-C/101-004<br>Section 4 | After<br>TMCL                                    | 3              | 3                 | 019     |

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| Qualification Plan | Device    | Paokage | Package & Assembly Location | No. of Lots |
|--------------------|-----------|---------|-----------------------------|-------------|
| Q20150495          | FDMF6840C | POBEN   | ASE-M                       | 2           |

| Test Description                  | Condition                             | 8tandard        | Duration   | 8ample<br>size | No. of<br>lots | Results |
|-----------------------------------|---------------------------------------|-----------------|------------|----------------|----------------|---------|
| Preconditioning, MSL 1            | Peak Temp (260°C)                     | JE8022-<br>A113 |            | 45, 77         | 6              | 0/366   |
| Highly Accelerated<br>Stress Test | Preconditioning,<br>85%RH, 110C, Blas | JE8022-<br>A110 | 300 hrs    | 45             | 8              | 0/135   |
| Temperature Cycle                 | Preconditioning,<br>-65C, 150C        | JE8022-<br>A104 | 100 cycles | 77             | ю              | 0/231   |

 Qualification Plan
 Device
 Package
 Package
 & Assembly Location
 No. of Lots

 Q20160052A
 FDMF8821B
 PQBFN
 Cebu
 3

| Test Description  | Condition                                | Standard                      | Duration                                   | 8ample<br>size | No. of<br>lots | Results |
|---|--|-------------------------------|--|----------------|----------------|---------|
| Preconditioning, MSL 1                                  | Peak Temp<br>(260°C)                     | JE8022-<br>A113               |  | 77             | 3              | 0/231   |
| Highly Accelerated Stress<br>Test                       | Preconditioning,<br>85%RH, 130C,<br>Blas | JE8D22-<br>A110               | 96hrs<br>192 hrs                           | 77             | 1              | 0/77    |
| Temperature Cycle                                       | Preconditioning,<br>-65C, 150C           | JE8D22-<br>A104               | 100 cycles<br>500 cycles<br>1000<br>cycles | 77             | 1              | 0/77    |
| High Temperature<br>Storage Life                        | Preconditioning,<br>150C                 | JE8D22-<br>A103               | 168 hrs<br>500 hrs<br>1000 hrs             | 77             | 1              | 0/77    |
| Destructive Physical<br>Analysis<br>(after 500cyc TMCL) | NA                                       | AEC-Q101-<br>004<br>Section 4 | After<br>TMCL                              | 2              | 1              | 0/2     |

The selection methodology of qualification vehicles is aligned with JESD47 and if automotive devices are impacted by the PCN the selection of qualification vehicles is also align with the requirements in AEC-Q100 or AEC-Q101

Please contact your local Customer Quality Engineer if you have any questions concerning this data.